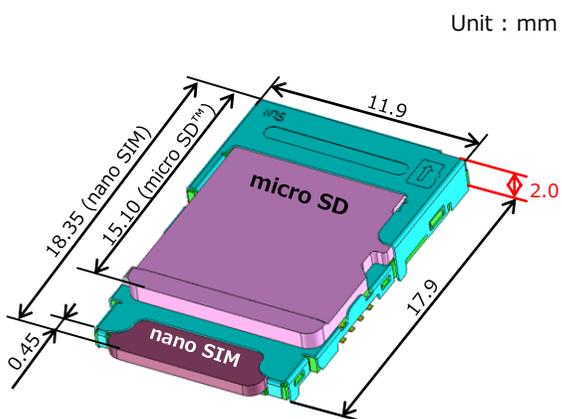


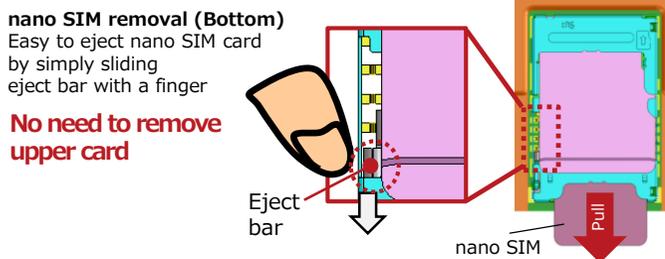
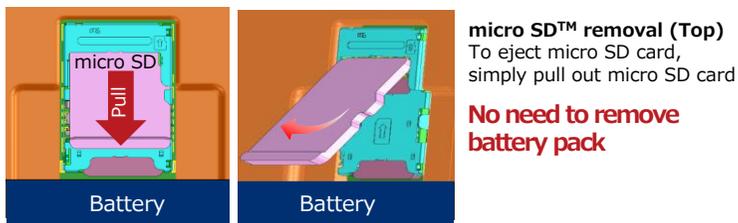
Features

- 1 Combo socket for nano SIM & micro SD™ cards produces a space saving design (Top slot : micro SD card, bottom slot : nano SIM card)
- 2 User friendly card removal design with top and bottom slot
- 3 Easy inspection with exposed contact design
- 4 User-friendly reverse card insertion prevention
- 5 Card detection switch for microSD and nano SIM cards

Dimensions



User friendly card removal design



Specifications

Contact Resistance	100mΩ Max.
Withstanding Voltage	500V AC for 1 minute
Mold Resistance	1,000MΩ Min. (500V DC)
Rated Current	0.5A
Rated Voltage	10V AC
Operating Temperature	-30℃ to +85℃
Mating cycles	10,000 times (micro SD) 5,000 times (nano Sim)

• RoHS compliant, Halogen-free product*

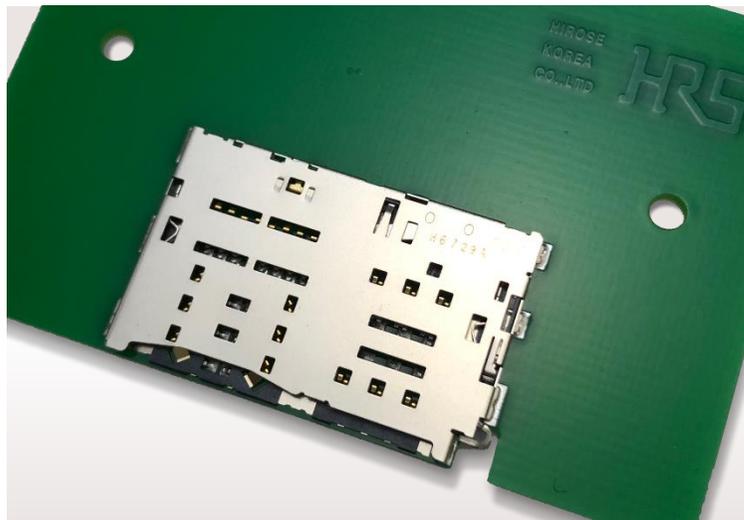
*This product satisfies halogen free requirements defined as 900ppm maximum chlorine, 900ppm maximum bromine, and 1500ppm maximum total of chlorine and bromine

※ Please contact Hirose's sales representative prior to adopting the products to in-vehicle devices.



Features

- 1 Easy to remove tray with eject pin
- 2 3 in 2 hybrid design provides various usage patterns.
- 3 Buckling prevention eliminates contact damage
- 4 Enhanced durability with ample eject bar thickness (40N)
- 5 Card detection switch



Dual card use design

Combo Type **Dual Sim card Type**

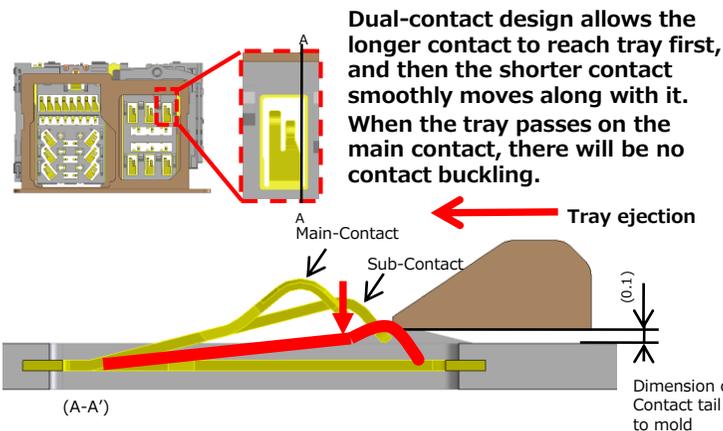
micro SD™ + nano SIM nano SIM × 2



⇒ Can be use in 2 cards patterns

*Note : Tray is not included and should be prepared by customers.

Buckling prevention design



Specifications

Contact Resistance	100mΩ Max.
Withstanding Voltage	500V AC for 1 minute
Mold Resistance	1000MΩ Min. (500V DC)
Rated Current	0.5A
Rated Voltage	10V AC
Operating Temperature	-30°C to +85°C
Mating cycles	3,000 times

• RoHS compliant, Halogen-free product*

*This product satisfies halogen free requirements defined as 900ppm maximum chlorine, 900ppm maximum bromine, and 1500ppm maximum total of chlorine and bromine

※ Please contact Hirose's sales representative prior to adopting the products to in-vehicle devices.